



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-12
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	FLORIANA SAN BIAGIO	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HYW8*V331AAL	A	ZS1A	2017-04-12
Amount	UoM	Unit type	ST ECOPACK Grade	
6.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ating is used or other bulk terminati	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	2x1.26x0.93	5	gull wing	
Comment	Package: W8 SOT 323 5LDS; MDF valid for TS331ICT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : REACH-12th January 2017

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HYW8*V331AAL					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.397	mg	supplier	die	Silicon (Si)	7440-21-3		0.385	mg	969773	64167
				supplier	metallization	Aluminium (Al)	7429-90-5		0.003	mg	7557	500
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	2519	167
				supplier	Passivation	Silicon Oxide	7631-86-9		0.008	mg	20151	1333
				supplier	alloy	Copper (Cu)	7440-50-8		2.549	mg	971788	424909
Leadframe	Copper & its alloys	2.623	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.060	mg	22875	10002
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.004	mg	1525	667
				supplier	alloy	Zinc (Zn)	7440-66-6		0.003	mg	1144	500
				supplier	metallization	Nickel (Ni)	7440-02-0		0.005	mg	1906	833
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	381	167
Die attach	Other Organic Materials	0.068	mg	supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	381	167
				supplier	glue	Epoxyde Bisphenol A Resin	25068-38-6		0.006	mg	88235	1000
				supplier	glue	Fused Silica	60676-86-0		0.021	mg	308824	3501
				supplier	glue	Ethylidiglycol acetate	112-15-2		0.015	mg	220588	2500
				supplier	glue	Aluminium oxide	1344-28-1		0.014	mg	205882	2334
Bonding wires	Precious metals	0.058	mg	supplier	glue	Bisphenol A diglycidyl ether polymer	25036-25-3		0.010	mg	147059	1667
				supplier	glue	Glycol ether ester	Proprietary		0.001	mg	14706	167
				supplier	glue	Diaminodiphenylsulfone	80-08-0		0.001	mg	14706	167
				supplier	wire	Gold (Au)	7440-57-5		0.058	mg	1000000	9668
				supplier	mold compound	Silica, vitreous	60676-86-0		2.457	mg	861199	409573
Encapsulation	Other Organic Materials	2.854	mg	supplier	mold compound	epoxy resin	25060-38-6		0.164	mg	57483	27338
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.141	mg	49422	23504
				supplier	mold compound	phenolic resin	29690-82-2		0.085	mg	29793	14169
				supplier	mold compound	carbon black	1333-86-4		0.006	mg	2103	1000